## SN75LBC241 LOW-POWER LinBiCMOS™ MULTIPLE DRIVERS AND RECEIVERS

SLLS137E - MAY 1992 - REVISED JANUARY 1999

- Operates With Single 5-V Power Supply
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU Recommendation V.28
- Improved Performance Replacement for MAX241
- Operates at Data Rates up to 100 kbit/s Over a 3-m Cable
- Low-Power Shutdown Mode . . . ≤1 μA Typ
- LinBiCMOS™ Process Technology
- Four Drivers and Five Receivers
- ±30-V Input Levels
- 3-State TTL/CMOS Receiver Outputs
- ±9-V Output Swing With a 5-V Supply
- Applications
  - TIA/EIA-232-F Interface
  - Battery-Powered Systems
  - Terminals
  - Modems
  - Computers
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages

#### (TOP VIEW) тоитз П 28 TOUT4 TOUT1 2 27 | RIN3 TOUT2 [] 3 26 ROUT3 RIN2 ∏ 4 25 SHUTDOWN ROUT2 5 24 | EN TIN2 **[]** 6 23 🛮 RIN4 TIN1 [] 7 22 ROUT4 ROUT1 **1**8 21 **∏** TIN4 RIN1 I 9 20 **∏** TIN3 GND [] 10 19 ROUT5 V<sub>CC</sub> ☐ 11 18 RIN5 17 🛮 V<sub>SS</sub> C1+ 1 12 V<sub>DD</sub> [] 13 16 C2-15 C2+ C1- [] 14

**DB OR DW PACKAGE** 

#### description

The SN75LBC241<sup>†</sup> is a low-power LinBiCMOS™ line-interface device containing four independent drivers and five receivers. It is designed as a plug-in replacement for the Maxim MAX241. The SN75LBC241 provides a capacitive-charge-pump voltage generator to produce RS-232 voltage levels from a 5-V supply. The charge-pump oscillator frequency is 20 kHz. Each receiver converts RS-232 inputs to 5-V TTL/CMOS levels. The receivers have a typical threshold of 1.2 V and a typical hysteresis of 0.5 V and can accept ±30-V inputs. Each driver converts TTL/CMOS input levels into RS-232 levels.

The SN75LBC241 includes a receiver, a 3-state control line, and a low-power shutdown control line. When the  $\overline{\text{EN}}$  line is high, receiver outputs are placed in the high-impedance state. When  $\overline{\text{EN}}$  is low, normal operation is enabled.

The shutdown mode reduces power dissipation to less than 5  $\mu$ W typically. In this mode, receiver outputs have high impedance, driver outputs are turned off, and the charge-pump circuit is turned off. When SHUTDOWN is high, the shutdown mode is enabled. When SHUTDOWN is low, normal operation is enabled.

This device has been designed to conform to TIA/EIA-232-F and ITU Recommendation V.28.

The SN75LBC241 has been designed using LinBiCMOS technology and cells contained in the Texas Instruments LinASIC™ library. Use of LinBiCMOS circuitry increases latch-up immunity in this device over an all-CMOS design.

The SN75LBC241 is characterized for operation from 0°C to 70°C.



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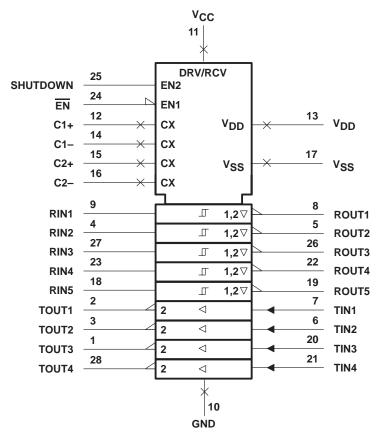
† Patent pending

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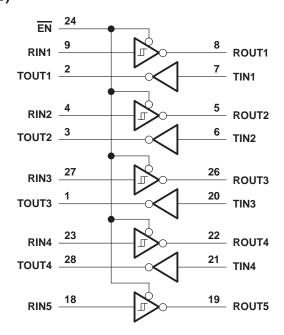
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#### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)





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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Input supply voltage range, V <sub>CC</sub> (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V <sub>DD</sub>	
Negative output supply voltage range, V <sub>SS</sub>	
Input voltage range, V <sub>I</sub> : Driver	
Receiver	±30 V
Output voltage range, V <sub>O</sub> : TOUT	$V_{SS} - 0.3 \text{ V to } V_{DD} + 0.3 \text{ V}$
ROUT	0.3 V to V <sub>CC</sub> + 0.3 V
Short-circuit duration: TOUT	
Continuous total dissipation	See Dissipation Rating Table
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the network ground terminal.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{$A$}} \leq 25^{\circ}\mbox{$C$}$ POWER RATING	OPERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING
DB	1348 mW	10.8 mW/°C	862 mW
DW	1603 mW	12.8 mW/°C	1026 mW

## recommended operating conditions

			MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>		4.5	5	5.5	V	
High level input voltage VIII	TIN	2			V	
	EN, SHUTDOWN	2.4				
Low-level input voltage, V <sub>IL</sub>		TIN, EN, SHUTDOWN			0.8	V
External charge-pump capacitor		C1–C4 (see Figure 1)	1			μF
External charge-pump capacitor voltage rating		C1, C3 (see Figure 1)	6.3			V
	C2, C4 (see Figure 1)	16			٧	
Receiver input voltage, V <sub>I</sub>					±30	V
Operating free-air temperature, T <sub>A</sub>		0		70	°C	

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## electrical characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CO	NDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT	
\/	High-level output voltage	TOUT	$R_L = 3 k\Omega$ to GN	ID, See Note 2	5 9			V	
VOH		ROUT	$I_{OH} = -1 \text{ mA}$		3.5			V	
\/ - ·	Low-level output voltage	TOUT	$R_L = 3 \text{ k}\Omega \text{ to GN}$	ID, See Note 3		_9 <sup>‡</sup>	-5	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
VOL		ROUT	$I_{OL} = 3.2 \text{ mA}$				0.4	V	
V <sub>IT+</sub>	Receiver positive-going input threshold voltage	RIN	V <sub>CC</sub> = 5 V,	T <sub>A</sub> = 25°C		1.7	2.4	V	
VIT-	Receiver negative-going input threshold voltage	RIN	V <sub>CC</sub> = 5 V,	T <sub>A</sub> = 25°C	0.8	1.2		V	
V <sub>hys</sub>	Input hysteresis voltage ( $V_{IT+} - V_{IT-}$ )	RIN	V <sub>CC</sub> = 5 V			0.5	1	V	
rį	Receiver input resistance	RIN	$V_{CC} = 5 V$ ,	T <sub>A</sub> = 25°C	3	5	7	kΩ	
r <sub>O</sub>	Output resistance	TOUT	$V_{DD} = V_{SS} = V_0$ $V_0 = \pm 2 \text{ V}$	CC = 0,	300			Ω	
los	Short circuit output current§	TOUT	V <sub>CC</sub> = 5.5 V,	VO = 0		±10		mA	
IIS	Short circuit input current	TIN	V <sub>I</sub> = 0				200	μΑ	
I <sub>CC</sub> Supply current		V <sub>CC</sub> = 5.5 V, T <sub>A</sub> All outputs open			4	8	mA		
	Зарріу сапені		All outputs open SHUTDOWN hig			1	10	mA	

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

- NOTES: 2. Total I<sub>OH</sub> drawn from TOUT1, TOUT2, TOUT3, TOUT4, and V<sub>DD</sub> terminals should not exceed 12 mA.
  - 3. Total IOL drawn from TOUT1, TOUT2, TOUT3, TOUT4, and VSS terminals should not exceed -12 mA.

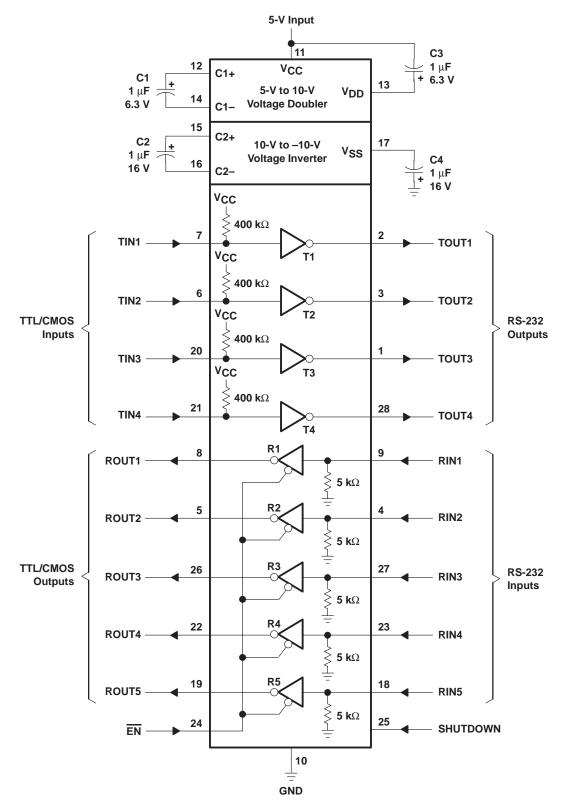
# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH(R)	Receiver propagation-delay time, low- to high-level output	See Figure 2		500		ns
tPHL(R)	Receiver propagation-delay time, high- to low-level output	See Figure 2		500		ns
<sup>t</sup> PZH	Receiver output-enable time to high level	See Figure 5		100		ns
tPZL	Receiver output-enable time to low level	See Figure 5		100		ns
<sup>t</sup> PHZ	Receiver output-disable time from high level	See Figure 5		50		ns
t <sub>PLZ</sub>	Receiver output-disable time from low level	See Figure 5		50		ns
SR	Driver slew rate	$R_L = 3 \text{ k}\Omega$ to 7 k $\Omega$ , $C_L = 2500 \text{ pF}$ , See Figure 4			30	V/μs
SR <sub>(tr)</sub>	Driver transition region slew rate	R <sub>L</sub> = 3 kΩ to 7 kΩ, C <sub>L</sub> = 2500 pF, See Figure 4	4	6	·	V/µs

<sup>‡</sup> The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic voltage

<sup>§</sup> Not more than one output should be shorted at one time.

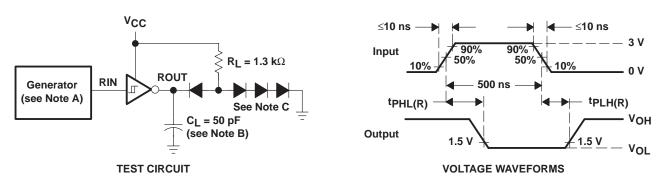
#### **APPLICATION INFORMATION**



**Figure 1. Typical Operating Circuit** 

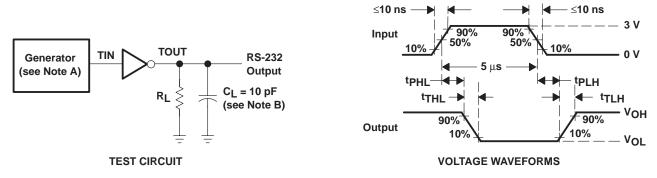


#### PARAMETER MEASUREMENT INFORMATION



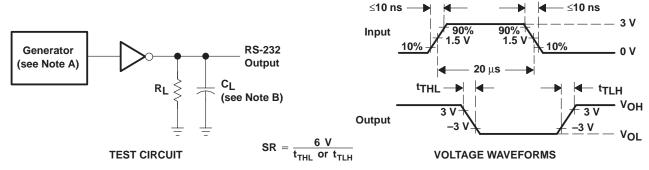
- NOTES: A. The pulse generator has the following characteristics:  $Z_{\Omega} = 50 \Omega$ , duty cycle  $\leq 50\%$ .
  - B. C<sub>I</sub> includes probe and jig capacitance.
  - C. All diodes are 1N3064 or equivalent.

Figure 2. Receiver Test Circuit and Waveforms for tpHL and tpLH Measurement



- NOTES: A. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , duty cycle  $\leq 50\%$ .
  - B. C<sub>L</sub> includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Waveforms for tpHL and tpLH Measurement (5-μs Input)

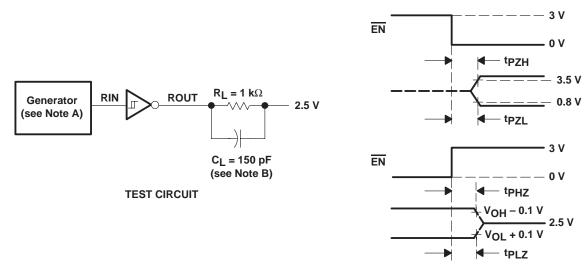


- NOTES: A. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , duty cycle  $\leq 50\%$ .
  - B. C<sub>L</sub> includes probe and jig capacitance.

Figure 4. Test Circuit and Waveforms for t<sub>THL</sub> and t<sub>TLH</sub> Measurement (20-μs Input)



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics:  $Z_0 = 50 \Omega$ , duty cycle  $\leq 50\%$ .

B. C<sub>L</sub> includes probe and jig capacitance.

Figure 5. Receiver Output Enable and Disable Timing

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